

Specification for Approval

PRODUCT NUMBER: RTD9922102000
PRODUCT DESCRIPTION: RGS15128128WR000

| |
|--------------------|
| CUSTOMER |
| |
| APPROVED BY |
| |
| DATE: |

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|----------------------------------|
| RITDISPLAY CORP. APPROVED |
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REVISION RECORD

| REV. | REVISION DESCRIPTION | REV. DATE | REMARK |
|------|--|--------------|-------------------------|
| X01 | ■ INITIAL RELEASE | 2008. 07. 10 | |
| X02 | <ul style="list-style-type: none"> ■ Modify definition of panel thickness ■ Add lifetime specifications ■ Modify D.C electrical characteristics ■ Add panel electrical specifications ■ Add application circuit | 2009. 04. 24 | Page 5, 6, 7, 8 & 16 |
| A01 | <ul style="list-style-type: none"> ■ Transfer from X version ■ Add the information of module weight ■ Modify seal color (white→black) ■ Add the packing specification | 2009. 12. 16 | Page 5, 18, 19 & 20 |
| A02 | ■ Add appendix of precautions for using the OLED module | 2014. 03. 31 | Page 25~34 |
| A03 | <ul style="list-style-type: none"> ■ Modify specification format ■ Modify CIE specifications ■ Add outgoing inspection provision | 2018. 05. 10 | Page 4, 6, 7, 8 & 21~26 |

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1. SCOPE

The purpose of this specification is to define the general provisions and quality requirements that apply to the supply of display cells manufactured by RiTdisplay. This document, together with the Module Assembly Drawing, is the highest-level specification for this product. It describes the product, identifies supporting documents and contains specifications.

2. WARRANTY

RiTdisplay warrants that the products delivered pursuant to this specification (or order) will conform to the agreed specifications for twelve (12) months from the shipping date ("Warranty Period"). RiTdisplay is obligated to repair or replace the products which are found to be defective or inconsistent with the specifications during the Warranty Period without charge, on condition that the products are stored **in the original packages at 25°C±5°C, 55%±10%RH** or used as the conditions specified in the specifications.

Nevertheless, RiTdisplay is not obligated to repair or replace the products without charge if the defects or inconsistency are caused by the force majeure or the reckless behaviors of the customer.

After the Warranty Period, all repairs or replacements of the products are subject to charge.

3. FEATURES

- Small molecular organic light emitting diode.
- Color : White
- Panel resolution : 128x128
- Driver IC : SSD1327
- Excellent quick response time.
- Extremely thin thickness for best mechanism design : 1.41 mm
- High contrast : 2000:1
- Wide viewing angle : 160°
- Strong environmental resistance.
- 8-bit 6800-series Parallel Interface, 8-bit 8080-series Parallel Interface, Serial Peripheral Interface, I²C Interface.
- Wide range of operating temperature : -40 to 70 °C
- Anti-glare polarizer.

4. MECHANICAL DATA

| NO | ITEM | SPECIFICATION | UNIT |
|----|-------------------|--------------------------------|-----------------|
| 1 | Dot Matrix | 128 x 128 | dot |
| 2 | Dot Size | 0.19 (W) x 0.19 (H) | mm ² |
| 3 | Dot Pitch | 0.21 (W) x 0.21 (H) | mm ² |
| 4 | Aperture Rate | 82 | % |
| 5 | Active Area | 26.86 (W) x 26.86 (H) | mm ² |
| 6 | Panel Size | 33.8 (W) x 36.5 (H) | mm ² |
| 7* | Panel Thickness | 1.22 ± 0.1 | mm |
| 8 | Module Size | 33.8 (W) x 43.7 (H) x 1.41 (T) | mm ³ |
| 9 | Diagonal A/A size | 1.5 | inch |
| 10 | Module Weight | 3.48 ± 10% | gram |

* Panel thickness includes substrate glass, cover glass and UV glue thickness.

5. MAXIMUM RATINGS

| ITEM | MIN | MAX | UNIT | Condition | Remark |
|-----------------------------|------|-----|------------------|--------------------------|-------------------|
| Supply Voltage (V_{CI}) | -0.3 | 4 | V | $T_a = 25^\circ\text{C}$ | IC maximum rating |
| Supply Voltage (V_{CC}) | 8 | 19 | V | $T_a = 25^\circ\text{C}$ | IC maximum rating |
| Operating Temp. | -40 | 70 | $^\circ\text{C}$ | - | - |
| Storage Temp | -40 | 85 | $^\circ\text{C}$ | - | Note (2) |

Note:

- (1) Maximum ratings are those values beyond which damages to the OLED module may occur. The OLED functional operation should be restricted to the limits in the section 6. Electrical Characteristics tables.
- (2) The defined temperature ranges do not include the polarizer. The maximum withstood temperature of the polarizer should be 80°C .

6. ELECTRICAL CHARACTERISTICS

6.1 D.C ELECTRICAL CHARACTERISTICS

| SYMBOL | PARAMETERS | TEST CONDITION | MIN | TYP | MAX | UNIT |
|----------|--------------------------------------|----------------------------|----------------|-----|----------------|------|
| V_{CC} | Driver power supply (for OLED panel) | $T_a = 25^\circ\text{C}$ | 14.5 | 15 | 15.5 | V |
| V_{CI} | Low voltage power supply | $T_a = 25^\circ\text{C}$ | 2.6 | - | 3.5 | V |
| V_{OH} | High logic output level | $I_{out}=100\mu\text{A}$, | $0.9^* V_{CI}$ | - | V_{CI} | V |
| V_{OL} | Low logic output level | $I_{out}=100\mu\text{A}$, | 0 | - | $0.1^* V_{CI}$ | V |
| V_{IH} | High logic input level | $I_{out}=100\mu\text{A}$, | $0.8^* V_{CI}$ | - | V_{CI} | V |
| V_{IL} | Low logic input level | $I_{out}=100\mu\text{A}$, | 0 | - | $0.2^* V_{CI}$ | V |

6.2 ELECTRO-OPTICAL CHARACTERISTICS

PANEL ELECTRICAL SPECIFICATIONS

| PARAMETER | MIN | TYP. | MAX | UNITS | COMMENTS |
|--|--------|------|------|-------------------|--------------------------------|
| Normal mode current consumption (ICC) | - | 32 | 34 | mA | All pixels on (1) |
| Standby mode current consumption (ICC) | - | 3 | 4 | mA | Standby mode 10% pixels on (2) |
| Normal mode power consumption | - | 480 | 510 | mW | All pixels on (1) |
| Standby mode power consumption | - | 45 | 60 | mW | Standby mode 10% pixels on (2) |
| Pixel Luminance | 70 | 90 | | cd/m ² | Display Average |
| Standby Luminance | | 20 | | cd/m ² | |
| CIE _x (White) | 0.23 | 0.27 | 0.31 | | CIE1931 |
| CIE _y (White) | 0.25 | 0.29 | 0.33 | | CIE1931 |
| Dark Room Contrast | 2000:1 | | | | |
| Viewing Angle | 160 | | | degree | |
| Response Time | | 10 | | μs | |

(1) Normal mode condition :

- Driving Voltage : 15V
- Contrast setting : 0x77
- Frame rate : 105Hz
- Duty setting : 1/128

(2) Standby mode condition :

- Driving Voltage : 15V
- Contrast setting : 0x14
- Frame rate : 105Hz
- Duty setting : 1/128

7. LIFETIME SPECIFICATION

| ITEM | MIN | UNIT | Condition | Remark |
|-----------|--------|------|--|----------|
| Life Time | 10,000 | Hrs | 100 cd/m ² , 50% alternating checkerboard | Note (1) |
| Life Time | 11,000 | Hrs | 90 cd/m ² , 50% alternating checkerboard | Note (2) |
| Life Time | 12,000 | Hrs | 80 cd/m ² , 50% alternating checkerboard | Note (3) |

Note:

(A) Under Vcc = 15V, Ta = 25°C, 50% RH.

(B) Life time is defined the amount of time when the luminance has decayed to less than 50% of the initial measured luminance.

(1) Setting of 100 cd/m² :

- Contrast setting : 0x9b
- Frame rate : 105Hz
- Duty setting : 1/128

(2) Setting of 90 cd/m² :

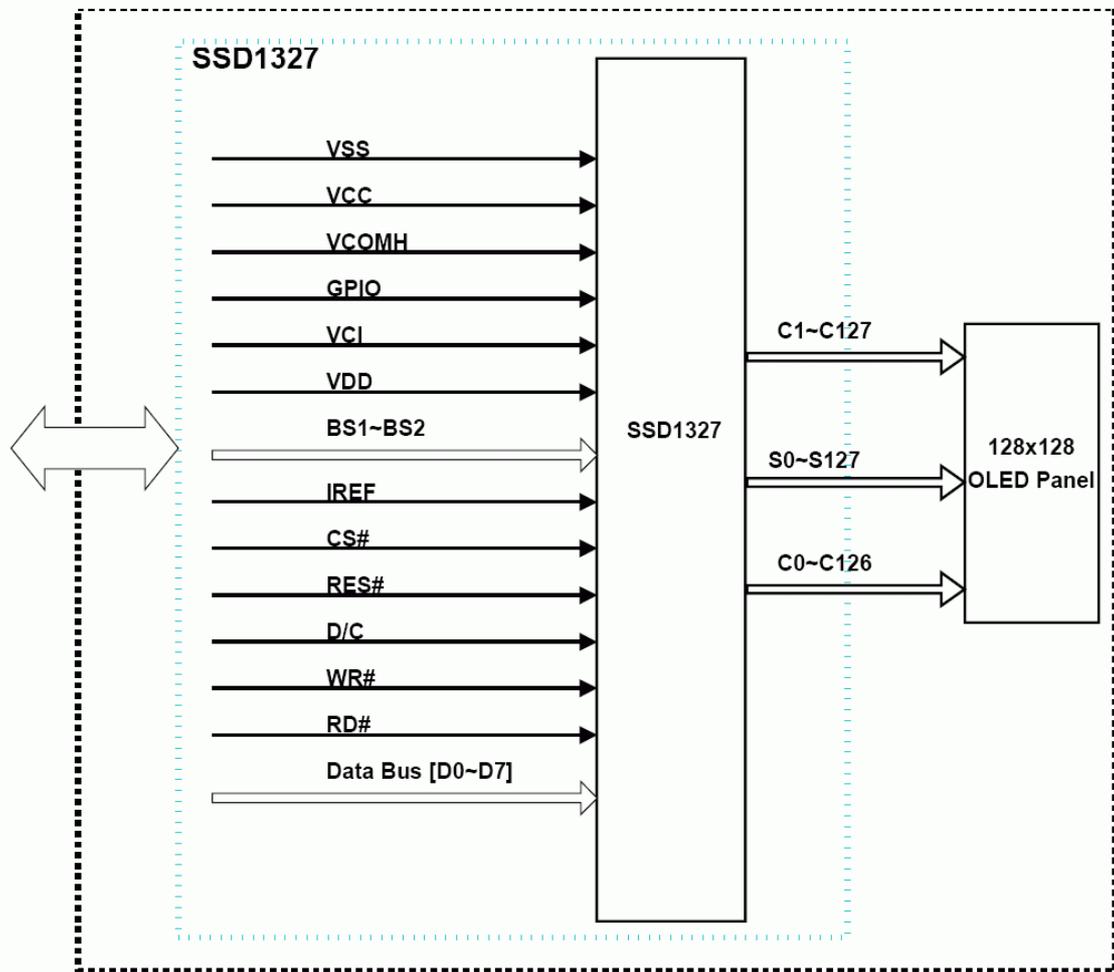
- Contrast setting : 0x77
- Frame rate : 105Hz
- Duty setting : 1/128

(3) Setting of 80 cd/m² :

- Contrast setting : 0x60
- Frame rate : 105Hz
- Duty setting : 1/128

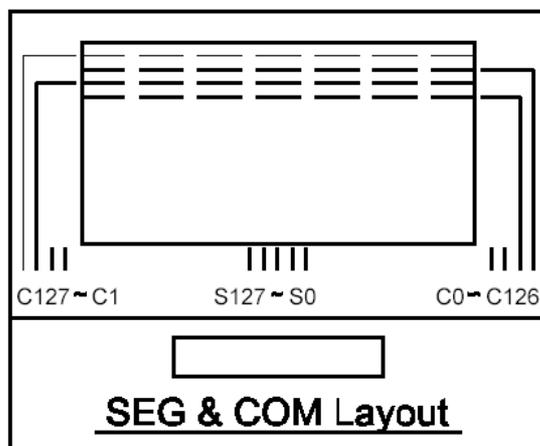
8. INTERFACE

8.1 FUNCTION BLOCK DIAGRAM



RiTdisplay 128X128 OLED Module

8.2 PANEL LAYOUT DIAGRAM



8.3 PIN ASSIGNMENTS

| PIN NAME | PIN NO | DESCRIPTION |
|----------|--------|--|
| VSS | 1 | Ground. |
| VCC | 2 | Power supply for analog circuit. |
| VCOMH | 3 | Com Voltage Output. A capacitor should be connected between this pin and V _{SS} . |
| GPIO | 4 | General I/O port. |
| VCI | 5 | Power supply for logic circuit. |
| VDD | 6 | A capacitor should be connected between this pin and V _{SS} . |
| BS1 | 7 | MCU bus interface selection pins. |
| BS2 | 8 | MCU bus interface selection pins. |
| VSS | 9 | Ground. |
| IREF | 10 | Reference current input pin. A resistor should be connected between this pin and V _{SS} . |
| CS# | 11 | Chip select input. |
| RES# | 12 | Reset signal input. When it's low, initialization of SSD1327 is executed. |
| D/C | 13 | Data/ Command control. Pull high for write/read display data. Pull low for write command or read status. |
| WR# | 14 | MCU interface input. Data write operation is initiated when it's pull low. |
| RD# | 15 | MCU interface input. Data read operation is initiated when it's pull low. |
| D0 | 16 | Data bus(for parallel interface) |
| D1 | 17 | |
| D2 | 18 | |
| D3 | 19 | |
| D4 | 20 | |
| D5 | 21 | |
| D6 | 22 | |
| D7 | 23 | |
| VCC | 24 | Power supply for analog circuit. |
| VSS | 25 | Ground. |

8.4 GRAPHIC DISPLAY DATA RAM ADDRESS MAP

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 128x128x4 bits. For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software. The GDDRAM address maps below tables show some examples on using the command “Set Re-map” A0h to re-map the GDDRAM. In the following tables, the lower nibble and higher nibble of D0, D1, D2 ... D8189, D8190, D8191 represent the 128x128 data bytes in the GDDRAM.

The GDDRAM map under the following condition:

- Command “Set Re-map” A0h is set to:
 Disable Column Address Re-map (A[0]=0)
 Disable Nibble Re-map (A[1]=0)
 Enable Horizontal Address Increment (A[2]=0)
 Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Data byte sequence: D0, D1, D2 ... D8191

GDDRAM address map 1

| | | SEG0 | SEG1 | SEG2 | SEG3 | | SEG124 | SEG125 | SEG126 | SEG127 | |
|--------|----|------------|------------|------------|------------|--|------------|------------|------------|------------|--|
| | | 00 | | 01 | | | 3E | | 3F | | |
| COM0 | 00 | D0[3:0] | D0[7:4] | D1[3:0] | D1[7:4] | | D62[3:0] | D62[7:4] | D63[3:0] | D63[7:4] | |
| COM1 | 01 | D64[3:0] | D64[7:4] | D65[3:0] | D65[7:4] | | D126[3:0] | D126[7:4] | D127[3:0] | D127[7:4] | |
| | | | | | | | | | | | |
| COM126 | 7E | D8064[3:0] | D8064[7:4] | D8065[3:0] | D8065[7:4] | | D8126[3:0] | D8126[7:4] | D8127[3:0] | D8127[7:4] | |
| COM127 | 7F | D8128[3:0] | D8128[7:4] | D8129[3:0] | D8129[7:4] | | D8190[3:0] | D8190[7:4] | D8191[3:0] | D8191[7:4] | |

SEG Outputs
Column Address
(HEX)

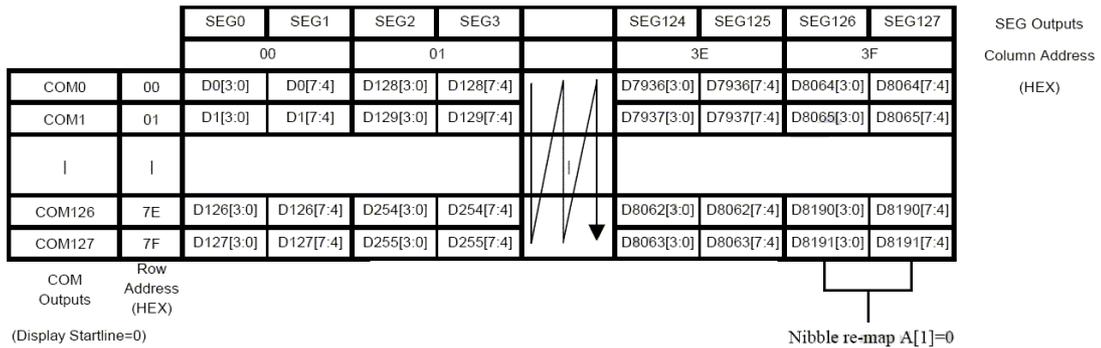
COM Outputs Row Address (HEX)

Nibble re-map A[1]=0

The GDDRAM map under the following condition:

- Command “Set Re-map” A0h is set to:
 Disable Column Address Re-map (A[0]=0)
 Disable Nibble Re-map (A[1]=0)
 Enable Vertical Address Increment (A[2]=1)
 Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Data byte sequence: D0, D1, D2 ... D8191

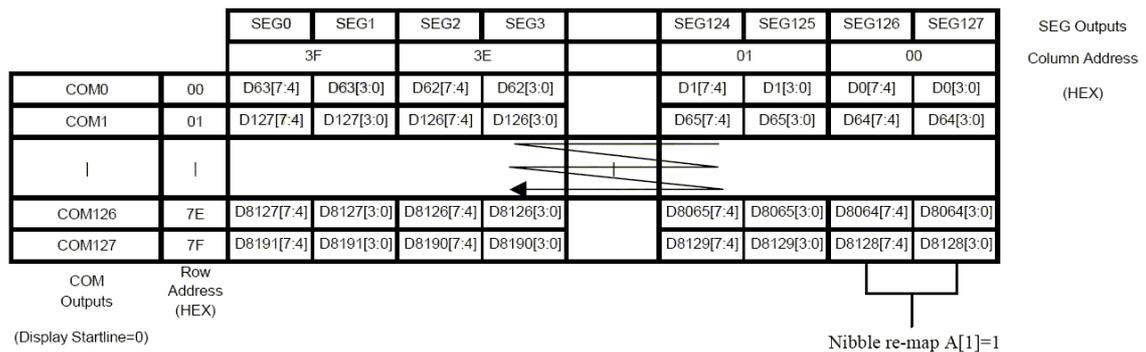
GDDRAM address map 2



The GDDRAM map under the following condition:

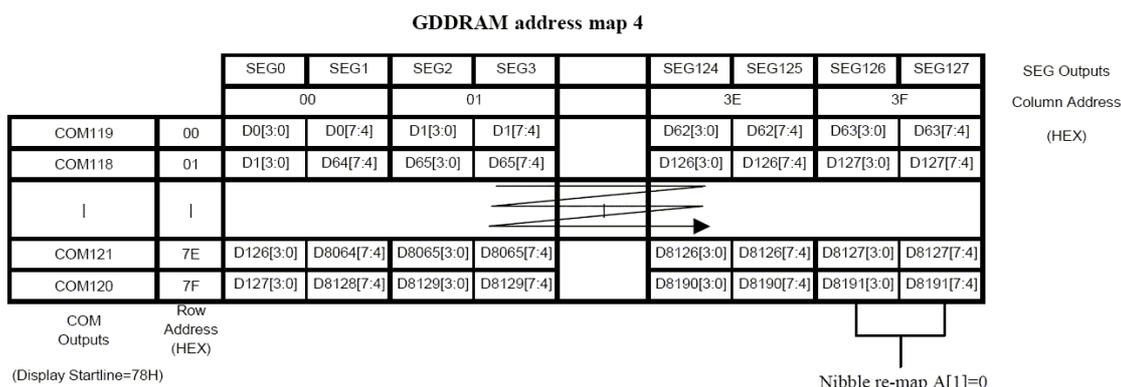
- Command “Set Re-map” A0h is set to:
 Enable Column Address Re-map (A[0]=1)
 Enable Nibble Re-map (A[1]=1)
 Enable Horizontal Address Increment (A[2]=0)
 Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Data byte sequence: D0, D1, D2 ... D8191

GDDRAM address map 3



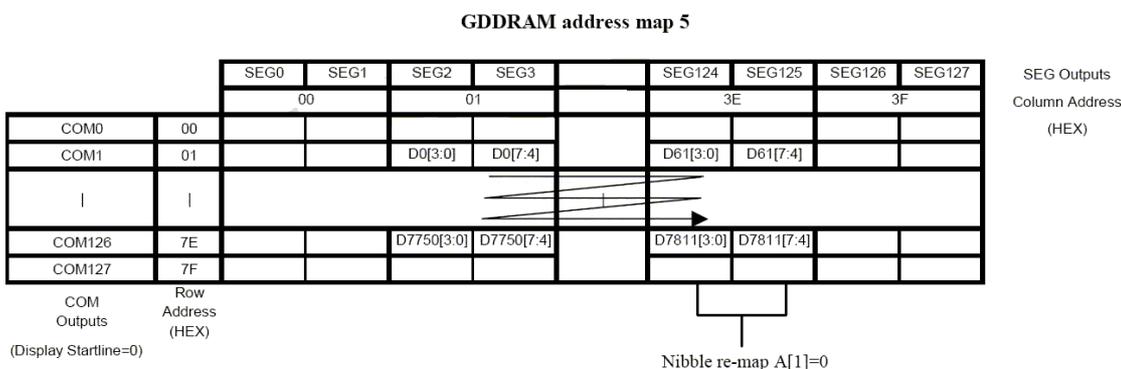
The example in which the display start line register is set to 10h with the following condition:

- Command “Set Re-map” A0h is set to:
 - Disable Column Address Re-map (A[0]=0)
 - Disable Nibble Re-map (A[1]=0)
 - Enable Horizontal Address Increment (A[2]=0)
 - Enable COM Re-map (A[4]=1)
- Display Start Line=78h (corresponds to COM119)
- Data byte sequence: D0, D1, D2 ... D8191



The GDDRAM map under the following condition:

- Command “Set Re-map” A0h is set to:
 - Disable Column Address Re-map (A[0]=0)
 - Disable Nibble Re-map (A[1]=0)
 - Enable Horizontal Address Increment (A[2]=0)
 - Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Column Start Address=01h
- Column End Address=3Eh
- Row Start Address=01h
- Row End Address=7Eh
- Data byte sequence: D0, D1, D2 ... D7811



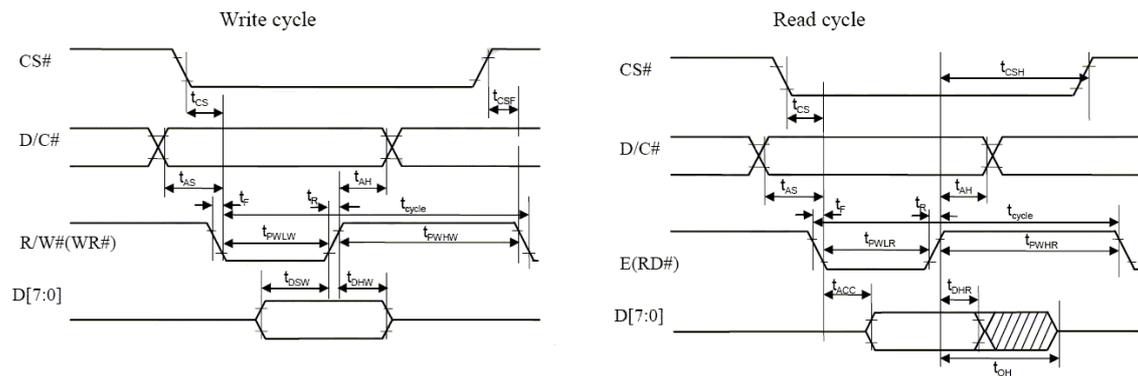
8.5 INTERFACE TIMING CHART

8080-Series MCU Parallel Interface Timing Characteristics

($V_{DD} - V_{SS} = 2.4$ to $2.6V$, $V_{CI} = 3.3V$, $T_A = 25^\circ C$)

| Symbol | Parameter | Min | Typ | Max | Unit |
|-------------|--------------------------------------|-----|-----|-----|------|
| t_{cycle} | Clock Cycle Time | 300 | - | - | ns |
| t_{AS} | Address Setup Time | 10 | - | - | ns |
| t_{AH} | Address Hold Time | 0 | - | - | ns |
| t_{DSW} | Write Data Setup Time | 40 | - | - | ns |
| t_{DHW} | Write Data Hold Time | 7 | - | - | ns |
| t_{DHR} | Read Data Hold Time | 20 | - | - | ns |
| t_{OH} | Output Disable Time | - | - | 70 | ns |
| t_{ACC} | Access Time | - | - | 140 | ns |
| t_{PWLR} | Read Low Time | 150 | - | - | ns |
| t_{PWLW} | Write Low Time | 60 | - | - | ns |
| t_{PWHR} | Read High Time | 60 | - | - | ns |
| t_{PWHW} | Write High Time | 60 | - | - | ns |
| t_R | Rise Time | - | - | 15 | ns |
| t_F | Fall Time | - | - | 15 | ns |
| t_{CS} | Chip select setup time | 0 | - | - | ns |
| t_{CSH} | Chip select hold time to read signal | 0 | - | - | ns |
| t_{CSF} | Chip select hold time | 20 | - | - | ns |

8080-series MCU parallel interface characteristics



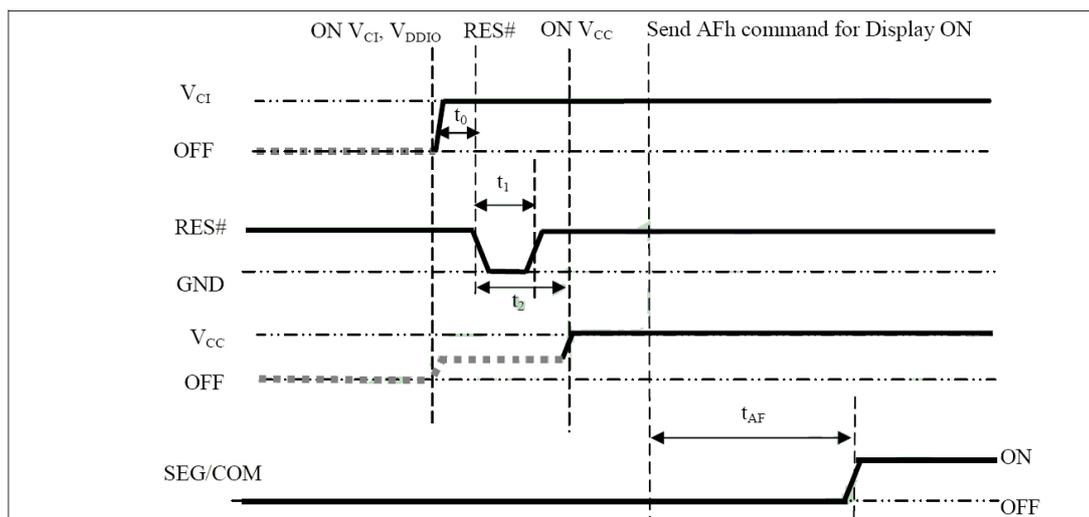
9. POWER ON / OFF SEQUENCE & APPLICATION CIRCUIT

9.1 POWER ON / OFF SEQUENCE

Power ON sequence:

1. Power ON V_{CI} .
2. After V_{CI} becomes stable, set wait time at least 1ms (t_0) for internal V_{DD} become stable. Then set RES# pin LOW (logic low) for at least 100us (t_1)⁽⁴⁾ and then HIGH (logic high).
3. After set RES# pin LOW (logic low), wait for at least 100us (t_2). Then Power ON V_{CC} .⁽¹⁾
4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 200ms(t_{AF}).

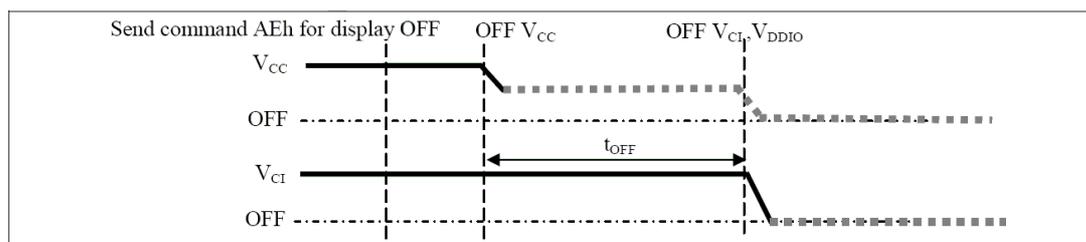
The Power ON sequence.



Power OFF sequence:

1. Send command AEh for display OFF.
2. Power OFF V_{CC} .^{(1), (2), (3)}
3. Wait for t_{OFF} . Power OFF V_{CI} . (where Minimum $t_{OFF}=80ms$ ⁽⁵⁾, Typical $t_{OFF}=100ms$)

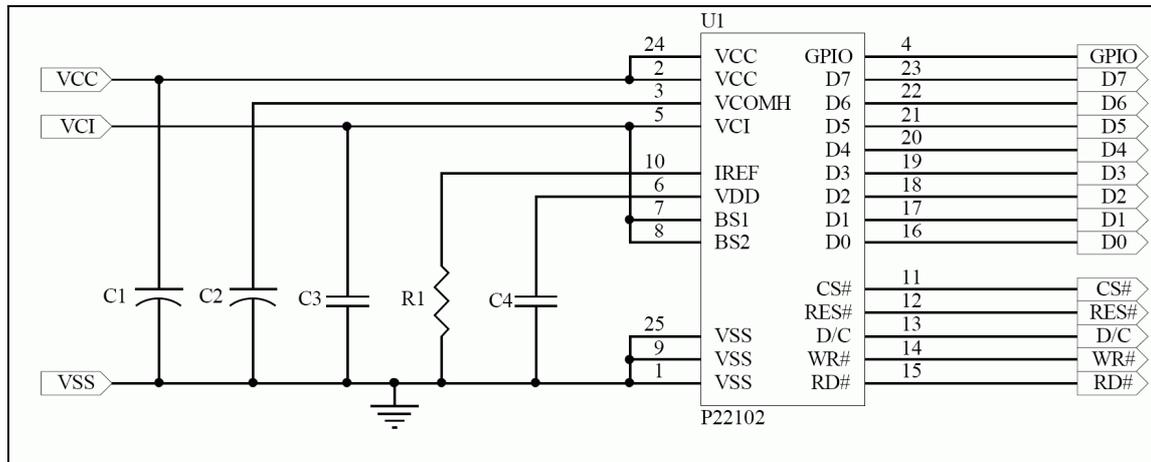
The Power OFF sequence



Note:

- (1) Since an ESD protection circuit is connected between V_{CI} and V_{CC} , V_{CC} becomes lower than V_{CI} whenever V_{CI} is ON and V_{CC} is OFF as shown in the dotted line of V_{CC} in above figures.
- (2) V_{CC} should be kept disable when it is OFF.
- (3) Power pins (V_{CI} , V_{CC}) can never be pulled to ground under any circumstance.
- (4) The register values are reset after t_1 .
- (5) V_{CI} should not be Power OFF before V_{CC} Power OFF

9.2 APPLICATION CIRCUIT



Component:

C1, C2: 4.7uF/35V(Tantalum type) or VISHAY (572D475X0025A2T)

C3, C4: 1uF/16V(0603)

R1: 1M ohm (0603) 1%

This circuit is for 8080 8bits interface.

9.3 COMMAND TABLE

Refer to IC Spec.: SSD1327

10. RELIABILITY TEST CONDITIONS

| No. | Items | Specification | Quantity |
|-----|--|---|----------|
| 1 | High temp. (Non-operation) | 85 °C, 240hrs | 5 |
| 2 | High temp. (Operation) | 70 °C, 120hrs | 5 |
| 3 | Low temp. (Operation) | -40 °C, 120hrs | 5 |
| 4 | High temp. / High humidity (Operation) | 65 °C, 90%RH, 120hrs | 5 |
| 5 | Thermal shock (Non-operation) | -40 °C ~85 °C (-40 °C /30min; transit /3min; 85 °C /30min; transit /3min) 1cycle: 66min, 100 cycles | 5 |
| 6 | Vibration | Frequency : 5~50HZ, 0.5G Scan rate : 1 oct/min Time : 2 hrs/axis Test axis : X, Y, Z | 1 Carton |
| 7 | Drop | Height: 120cm Sequence : 1 angle 、 3 edges and 6 faces Cycles: 1 | 1 Carton |
| 8 | ESD (Non-operation) | Air discharge model, ±8kV, 10 times | 5 |

Test and measurement conditions

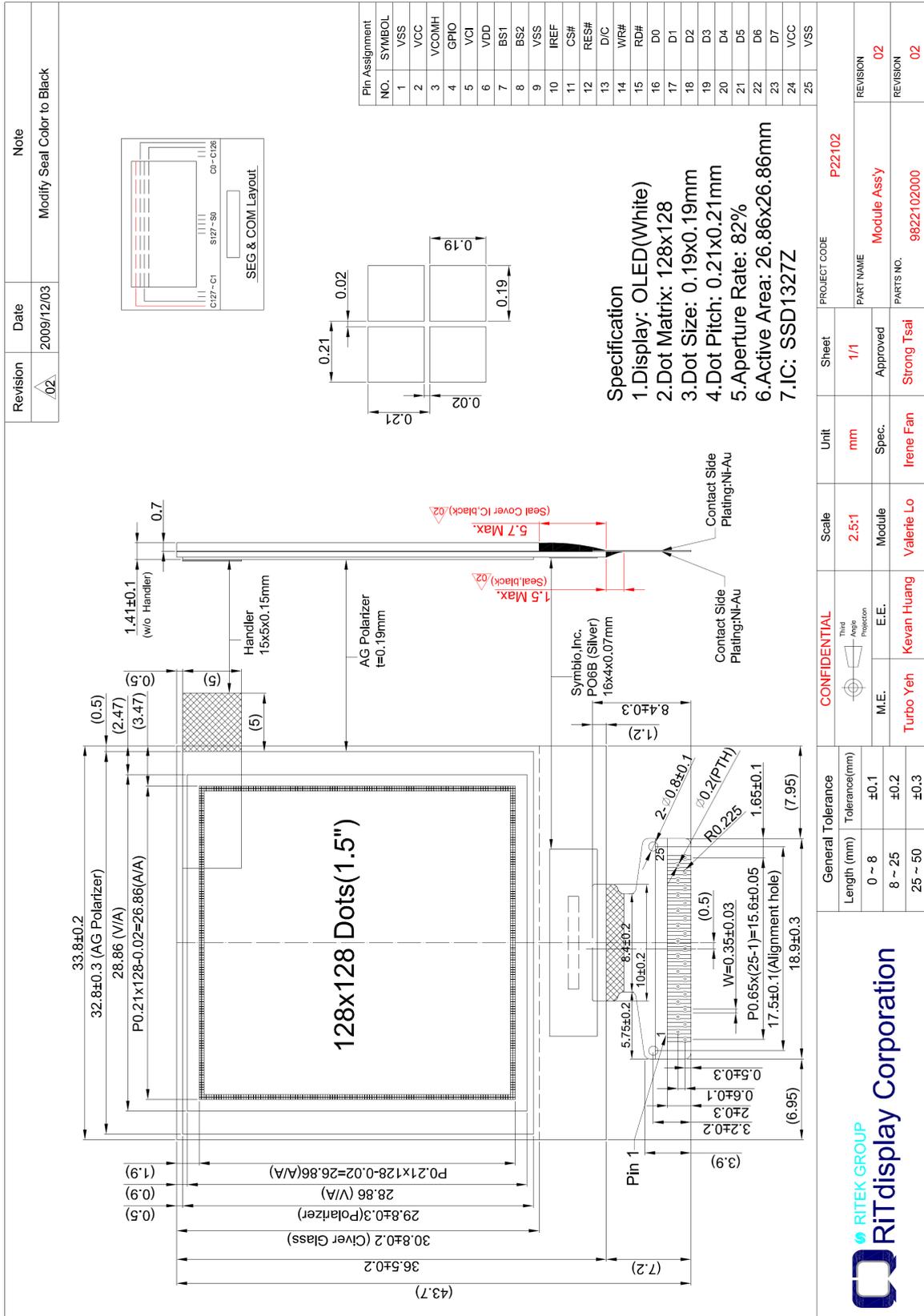
1. All measurements shall not be started until the specimens attain to temperature stability.
2. The degradation of Polarizer are ignored for item 1, 4 & 5.

Evaluation criteria

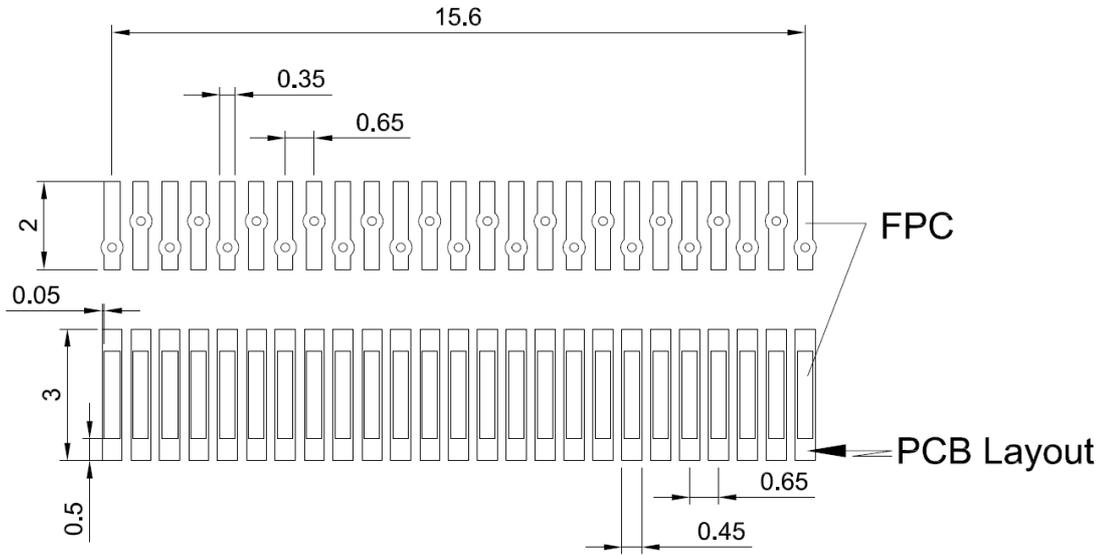
1. The function test is OK.
2. No observable defects.
3. Luminance: > 50% of initial value.
4. Current consumption: within ± 50% of initial value.

11. EXTERNAL DIMENSION

11.1 MODULE ASSEMBLY DRAWING



11.2 FOOTPRINT DRAWING



12. PACKING SPECIFICATION

| Revision | Date | Note |
|----------|------------|--------------------------|
| 01 | 2009/12/07 | Packing Tray Instruction |

9822102000
Module Ass'y For P22102 x30 pcs

1 Face up ,Rotate packing
面朝上,旋轉放置

3008000362
Tray 330x270x8.7mm T=0.7mm,PS,P22102

3010000002
5G 矽膠劑
x1 pcs(empty)

3010000002
5G 矽膠劑
x4 pcs

3003000012
Vacuum Bag ONY/LDPE
真空包裝袋 ONY/LDPE
480x285x90

9 Tape
膠帶
3208000125
Tray =21 pcs

5 3003000016
Antistatic Bubble bag 440x(350+450)mm
抗靜電氣泡袋

7 3000000009
Carton 385x305x203mm

6 3001000005
Pizza Box 345x285x88,B corrugated
B 浪

8 3006000000
Label 標籤
Label x1 pcs
Label x2 pcs

3008000125
Tape
膠帶

Rotatate stack
旋轉堆疊

Vacuum packing : 4 sec
抽真空:4秒

General Tolerance

| Length (mm) | Tolerance(mm) |
|-------------|---------------|
| 0 ~ 8 | ±0.1 |
| 8 ~ 25 | ±0.2 |
| 25 ~ 50 | ±0.3 |

| ITEM | PART No. | DESC | QTY |
|------|------------|---------------------------------------|------|
| 1 | 9822102000 | Module Ass'y For P22102 | 1200 |
| 2 | 3008000362 | Tray 330x270x8.7 T:0.7mm PS P22102 | 42 |
| 3 | 3010000002 | 5G Silica Gel Desiccants | 8 |
| 4 | 3003000012 | Vacuum Bag ONY/LDPE 480x285x90 | 2 |
| 5 | 3003000016 | Antistatic Bubble bag 440x(350+450)mm | 2 |
| 6 | 3001000005 | Pizza Box 345x285x88,B corrugated | 2 |
| 7 | 3000000009 | Carton 385x305x203mm | 1 |
| 8 | 3006000000 | Label | 3 |
| 9 | 3208000125 | Tape, Wt=48mm, L=910cm | |

| CONFIDENTIAL | | Scale | Unit | Sheet | PROJECT CODE |
|--------------|------------|-----------|-----------|--------------|--------------------------|
| M.E. | E.E. | 1:15 | mm | 1/1 | P22102 |
| Turbo Yeh | Allan Yang | Module | Spec. | Approved | PART NAME |
| | | Kelly Hsu | Irene Fan | Strong T sai | Packing Tray Instruction |
| | | | | | PARTS NO. |
| | | | | | 9922102000 |
| | | | | | VERSION |
| | | | | | 01 |
| | | | | | VERSION |
| | | | | | 01 |

RITEK GROUP
RiTdisplay Corporation

13. OUTGOING INSPECTION PROVISION

1. 抽樣方法 / SAMPLING METHOD

- (1) MIL-STD-1916 / 驗證水準 level III / 正常檢驗 / 單次樣品檢驗
MIL-STD-1916 / inspection level III / normal inspection / single sample inspection
- (2) 主要缺陷 Level III ; 次要缺陷 Level II
Major Level III ; Minor Level II

| MIL-STD-1916 樣本代字對照表 | | | | | | | |
|----------------------|-----------|----|---|----|-----|----|---|
| 批量 | 驗證水準 (VL) | | | | | | |
| | VII | VI | V | IV | III | II | I |
| 2 ~ 170 | A | A | A | A | A | A | A |
| 171 ~ 288 | A | A | A | A | A | A | B |
| 289 ~ 544 | A | A | A | A | A | B | C |
| 545 ~ 960 | A | A | A | A | B | C | D |
| 961 ~ 1632 | A | A | A | B | C | D | E |
| 1633 ~ 3072 | A | A | B | C | D | E | E |
| 3073 ~ 5440 | A | B | C | D | E | E | E |
| 5441 ~ 9216 | B | C | D | E | E | E | E |
| 9217 ~ 17408 | C | D | E | E | E | E | E |
| 17409 ~ 30720 | D | E | E | E | E | E | E |
| ≥ 30721 | E | E | E | E | E | E | E |

2. 檢驗條件 / INSPECTION CONDITION

檢查和測量在下列條件下進行的，除非另有規定。

The inspection and measurement are performed under the following conditions, unless otherwise specified.

溫度 / Temperature: 25±5 °C

濕度 / Humidity: 50±10%R.H.

壓力 / Pressure: 860~1060hPa (mbar)

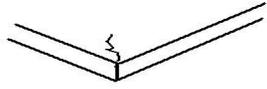
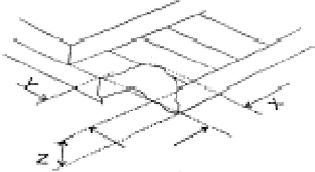
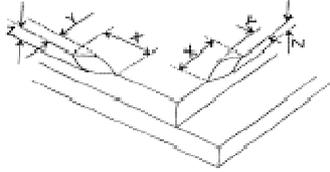
檢驗員拿的面板和眼睛之間的距離 / Distance between the panel and eyes of the inspector ≥ 30cm

3. 品質檢驗規格 / SPECIFICATION FOR QUALITY CHECK

3.1 缺陷分類 / DEFECT CLASSIFICATION

| 嚴重度 Severity | 檢驗項目 Inspection Item | 缺陷 Defect | 備註 Remark |
|----------------------|-------------------------|--|------------------------------|
| 主要缺陷 Major Defect | 1. 面板 Panel | (1) 無顯示 Non-displaying | |
| | | (2) 線缺陷 Line defects | |
| | | (3) 故障 Malfunction | |
| | | (4) 玻璃破損 Glass cracked | |
| | 2. 軟板 Film | (1) 軟板尺寸超規 Film dimension out of specification | 不能組裝 Can not be assembled |
| | 3. 尺寸 Dimension | (1) 外形尺寸超規 Outline dimension out of specification | |
| 次要缺陷 Minor Defect | 1. 面板 Panel | (1) 玻璃刮傷 Glass scratch | 外觀缺陷 Appearance defect |
| | | (2) 玻璃切割異常 Glass cutting NG | |
| | | (3) 玻璃崩邊、崩角 Glass chip | |
| | 2. 偏光板 Polarizer | (1) 偏光板刮傷 Polarizer scratch | |
| | | (2) 表面汙漬 Stains on surface | |
| | | (3) 偏光板氣泡 Polarizer bubbles | |
| | 3. 顯示 Displaying | (1) 暗點、亮點、髒污 Dim spot·Bright spot·dust | |
| | 4. 軟板 Film | (1) 損傷 Damage | |
| | | (2) 異物 Foreign material | |

3.2 出貨規格 / OUTGOING SPECIFICATION

| 項目 Item | 描述 Description | 標準 Criterion | 允收 水準 AQL | | | | | | | | | | | | | | | |
|--------------------------|---|---|--|-------------------------|--|---------------|--------------|--------------|----------------------|------------|---|------------|-------|-----------|---------------------|-------|--------------|-------------|
| I. 面板 Panel | 1. 玻璃刮傷 Glass scratch | <table border="1"> <thead> <tr> <th>寬 / Width (mm) W</th> <th>長 / Length (mm) L</th> <th>容許個數 number of pieces permitted</th> </tr> </thead> <tbody> <tr> <td>$W \leq 0.03$</td> <td>忽略 Ignore</td> <td>忽略 Ignore</td> </tr> <tr> <td>$0.03 < W \leq 0.05$</td> <td>$L \leq 1$</td> <td>1</td> </tr> <tr> <td>$0.05 < W$</td> <td>-----</td> <td>無 None</td> </tr> <tr> <td>顯示區外 beyond A.A.</td> <td>-----</td> <td>忽略 Ignore</td> </tr> </tbody> </table> | 寬 / Width (mm) W | 長 / Length (mm) L | 容許個數 number of pieces permitted | $W \leq 0.03$ | 忽略 Ignore | 忽略 Ignore | $0.03 < W \leq 0.05$ | $L \leq 1$ | 1 | $0.05 < W$ | ----- | 無 None | 顯示區外 beyond A.A. | ----- | 忽略 Ignore | 次要 Minor |
| | 寬 / Width (mm) W | 長 / Length (mm) L | 容許個數 number of pieces permitted | | | | | | | | | | | | | | | |
| | $W \leq 0.03$ | 忽略 Ignore | 忽略 Ignore | | | | | | | | | | | | | | | |
| $0.03 < W \leq 0.05$ | $L \leq 1$ | 1 | | | | | | | | | | | | | | | | |
| $0.05 < W$ | ----- | 無 None | | | | | | | | | | | | | | | | |
| 顯示區外 beyond A.A. | ----- | 忽略 Ignore | | | | | | | | | | | | | | | | |
| 2. 玻璃破損 Glass crack | <p>(1) 裂紋 / Crack 擴展裂紋是不能接受的。 Propagation crack is not acceptable.</p>  | 主要 Major | | | | | | | | | | | | | | | | |
| 3. 玻璃崩邊、崩角 Glass chip | <p>(1) 崩角 / Chip on corner</p>  <p>(2) 崩邊 / Chip on edge</p>  | 次要 Minor | | | | | | | | | | | | | | | | |

| 項目 Item | 描述 Description | 標準 Criterion | 允收 水準 AQL | | | | | | | | | | | | | | | | |
|-----------------------|---------------------------------------|--|-------------------------|---------------------------------------|-----------------------|--------------|-----------------------|------|--------------|------|---------------------|--------------|-------------|------|---|----|---|----|-------------|
| I. 面板 Panel | 3. 玻璃崩邊、崩角 Glass chip | <table border="1"> <thead> <tr> <th>崩角 Chip on corner</th> <th>Size (mm)</th> <th>崩邊 Chip on edge</th> <th>Size (mm)</th> </tr> </thead> <tbody> <tr> <td>X</td> <td>≤1.5</td> <td>X</td> <td>≤3.0</td> </tr> <tr> <td>Y</td> <td>≤2.0</td> <td>Y</td> <td>≤1.0</td> </tr> <tr> <td>Z</td> <td>≤t</td> <td>Z</td> <td>≤t</td> </tr> </tbody> </table> <p>備註 / Note: 1. t = 玻璃厚度 t = glass thickness 2. 崩邊或崩角延伸到 ITO 導線是不能接受的。 Chip on the corner extending into the ITO contact is not acceptable.</p> | 崩角 Chip on corner | Size (mm) | 崩邊 Chip on edge | Size (mm) | X | ≤1.5 | X | ≤3.0 | Y | ≤2.0 | Y | ≤1.0 | Z | ≤t | Z | ≤t | 次要 Minor |
| | 崩角 Chip on corner | Size (mm) | 崩邊 Chip on edge | Size (mm) | | | | | | | | | | | | | | | |
| X | ≤1.5 | X | ≤3.0 | | | | | | | | | | | | | | | | |
| Y | ≤2.0 | Y | ≤1.0 | | | | | | | | | | | | | | | | |
| Z | ≤t | Z | ≤t | | | | | | | | | | | | | | | | |
| | 4. 尺寸 Dimension | 請參閱圖紙的規範。 Refer to the drawing of the spec | 主要 Major | | | | | | | | | | | | | | | | |
| II. 偏光板 Polarizer | 1. 刮傷 Scratch | 點狀按照“項目 II-3 偏光板氣泡”的標準。 Spot type in accordance with the criteria of “Item II-3. Polarizer bubble”. 線狀按照“項目 I-1 玻璃刮傷”的標準。 Line type in accordance with the criteria of “Item I-1. Glass scratch”. | 次要 Minor | | | | | | | | | | | | | | | | |
| | 2. 表面汙漬 Stains on surface | 表面汙漬無法用軟布或類似的清潔物輕輕擦拭 去除。 Stains cannot be removed even when wiped lightly with a soft cloth or similar cleaning. | 次要 Minor | | | | | | | | | | | | | | | | |
| | 3. 偏光板氣泡 Polarizer bubble | <p style="text-align: right;">(mm)</p> <table border="1"> <thead> <tr> <th>尺寸 Size</th> <th>容許個數 number of pieces permitted</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>忽略 Ignore</td> </tr> <tr> <td>$0.2 < \Phi \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < \Phi$</td> <td>0</td> </tr> <tr> <td>顯示區外 beyond A.A.</td> <td>忽略 Ignore</td> </tr> </tbody> </table> | 尺寸 Size | 容許個數 number of pieces permitted | $\Phi \leq 0.2$ | 忽略 Ignore | $0.2 < \Phi \leq 0.5$ | 2 | $0.5 < \Phi$ | 0 | 顯示區外 beyond A.A. | 忽略 Ignore | 次要 Minor | | | | | | |
| 尺寸 Size | 容許個數 number of pieces permitted | | | | | | | | | | | | | | | | | | |
| $\Phi \leq 0.2$ | 忽略 Ignore | | | | | | | | | | | | | | | | | | |
| $0.2 < \Phi \leq 0.5$ | 2 | | | | | | | | | | | | | | | | | | |
| $0.5 < \Phi$ | 0 | | | | | | | | | | | | | | | | | | |
| 顯示區外 beyond A.A. | 忽略 Ignore | | | | | | | | | | | | | | | | | | |

| 項目 Item | 描述 Description | 標準 Criterion | 允收 水準 AQL | | | | | | | | | | | |
|------------------------------------|--|--|------------------------------------|---------------------------------------|--------------|--------------|---------------------|---|---------------------|---|-----------|---|---------------------|--------------|
| III. 顯示 Displaying | 1. 耗電 Power consumption | 該模組的工作電流消耗不應超出產品規格書的規範。 The module operating current consumption should not go beyond the standard indicated in Product Specification | 主要 Major | | | | | | | | | | | |
| | 2. 像素尺寸 Pixel size | 顯示像素的尺寸的公差應規格的±25%之內。 The tolerance of display pixel dimension should be within ±25% of specification. | 次要 Minor | | | | | | | | | | | |
| | 3. 顏色 Color | 依據產品規格。 Refer to the product specification. | 主要 Major | | | | | | | | | | | |
| | 4. 亮度 Luminance | 依據產品規格。 Refer to the product specification. | 主要 Major | | | | | | | | | | | |
| | 5. 暗點、亮點、 髒污 Dimming spot、Lighting spot、Dust | 1. <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>平均直徑 Average diameter D:(mm)</th> <th>容許個數 number of pieces permitted</th> </tr> </thead> <tbody> <tr> <td>$D \leq 0.1$</td> <td>忽略 Ignore</td> </tr> <tr> <td>$0.1 < D \leq 0.15$</td> <td>1</td> </tr> <tr> <td>$0.15 < D \leq 0.2$</td> <td>1</td> </tr> <tr> <td>$0.2 < D$</td> <td>0</td> </tr> <tr> <td>顯示區外 beyond A.A.</td> <td>忽略 Ignore</td> </tr> </tbody> </table> <p>D=(長邊直徑 + 短邊直徑)/2 D=(long diameter + short diameter)/2 像素暗點是不允許。 Pixel off is not allowed.</p> | 平均直徑 Average diameter D:(mm) | 容許個數 number of pieces permitted | $D \leq 0.1$ | 忽略 Ignore | $0.1 < D \leq 0.15$ | 1 | $0.15 < D \leq 0.2$ | 1 | $0.2 < D$ | 0 | 顯示區外 beyond A.A. | 忽略 Ignore |
| 平均直徑 Average diameter D:(mm) | 容許個數 number of pieces permitted | | | | | | | | | | | | | |
| $D \leq 0.1$ | 忽略 Ignore | | | | | | | | | | | | | |
| $0.1 < D \leq 0.15$ | 1 | | | | | | | | | | | | | |
| $0.15 < D \leq 0.2$ | 1 | | | | | | | | | | | | | |
| $0.2 < D$ | 0 | | | | | | | | | | | | | |
| 顯示區外 beyond A.A. | 忽略 Ignore | | | | | | | | | | | | | |

| 項目 Item | 描述 Description | 標準 Criterion | 允收 水準 AQL | | |
|-----------------------|--|---|-----------------|----------------------|--|
| III. 顯示 Displaying | 5. 暗點、亮點、 髒污 Dimming spot、Lighting spot、Dust | 2. | 次要 Minor | | |
| | | 寬 width(mm) W | | 長 length(mm) L | 容許個數 number of pieces permitted |
| | | $W \leq 0.03$ | | 忽略 Ignore | 忽略 Ignore |
| | | $0.03 < W \leq 0.05$ | | $L \leq 1$ | 3 |
| | | $0.05 < W$ | | ----- | 無 None |
| | 顯示區外 beyond A.A. | ----- | 忽略 Ignore | | |
| IV. 軟板 Film | 1. 尺寸 Dimension | 軟板尺寸超規。 Film dimension out of Spec. | 主要 Major | | |
| | 2. 損傷 Damage | 破損；深刮傷；深摺痕；深壓痕或其他損害是不能接受的。 Crack; deep scratch; deep fold; deep pressure mark or other damage is not acceptable. | 次要 Minor | | |
| | 3. 異物 Foreign material | 導電異物附著在導線，軟板和玻璃之間的異物是不能接受的。 Conductive foreign material sticking to the leads, foreign material between film and glass are not acceptable. | 次要 Minor | | |

14. APPENDIXES

APPENDIX 1: DEFINITIONS

A. DEFINITION OF CHROMATICITY COORDINATE

The chromaticity coordinate is defined as the coordinate value on the CIE 1931 color chart for R, G, B, W.

B. DEFINITION OF CONTRAST RATIO

The contrast ratio is defined as the following formula:

$$\text{Contrast Ratio} = \frac{\text{Luminance of all pixels on measurement}}{\text{Luminance of all pixels off measurement}}$$

C. DEFINITION OF RESPONSE TIME

The definition of turn-on response time T_r is the time interval between a pixel reaching 10% of steady state luminance and 90% of steady state luminance. The definition of turn-off response time T_f is the time interval between a pixel reaching 90% of steady state luminance and 10% of steady state luminance. It is shown in Figure 2.

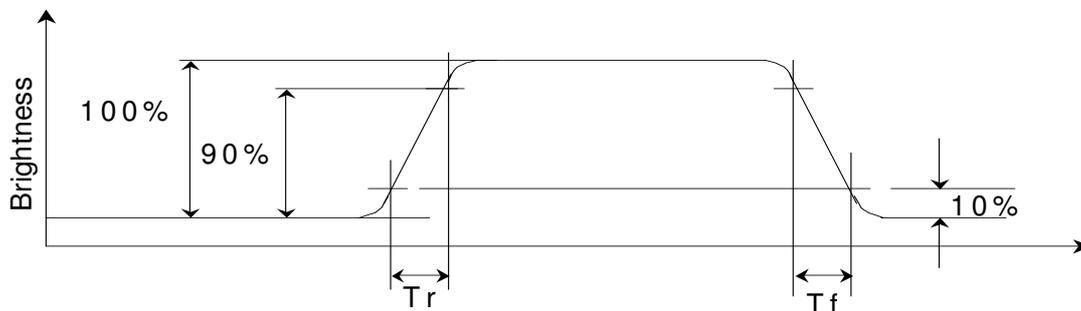


Figure 2 Response time

D. DEFINITION OF VIEWING ANGLE

The viewing angle is defined as Figure 3. Horizontal and vertical (H & V) angles are determined for viewing directions where luminance varies by 50% of the perpendicular value.

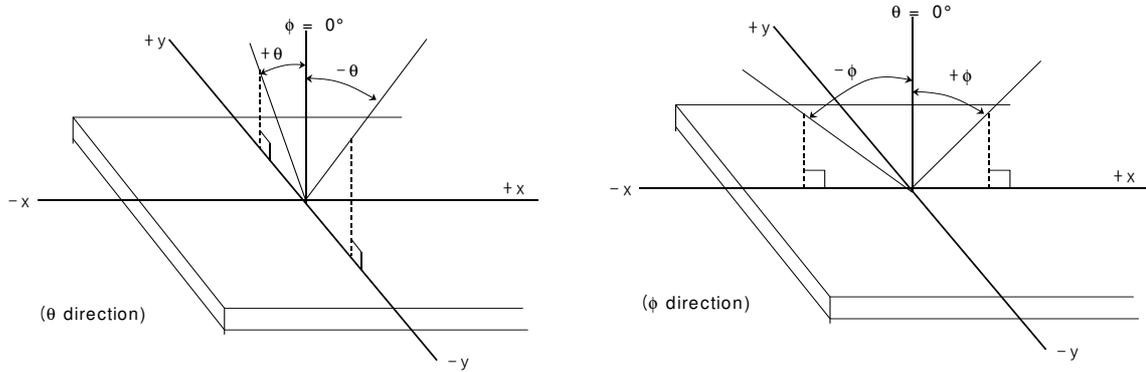
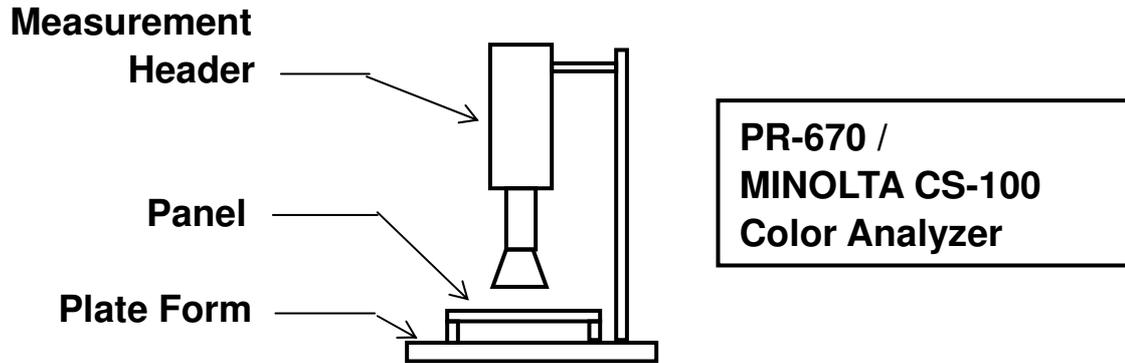


Figure 3 Viewing angle

APPENDIX 2: MEASUREMENT APPARATUS

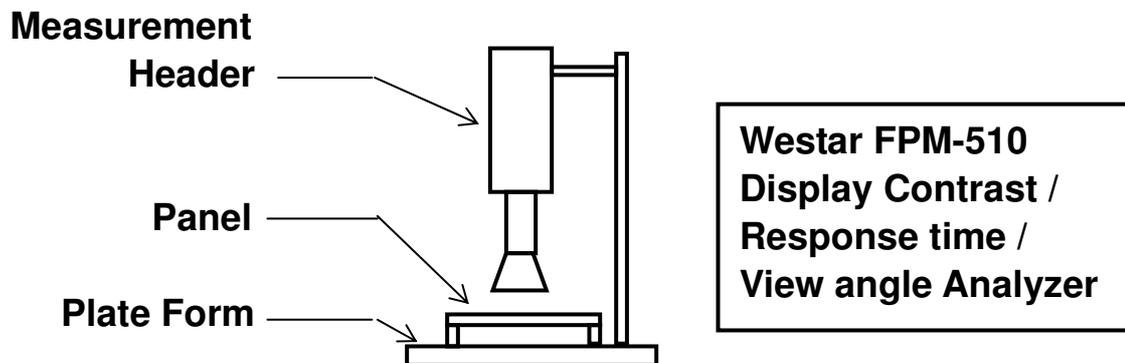
A. LUMINANCE/COLOR COORDINATE

PHOTO RESEARCH PR-670, MINOLTA CS-100

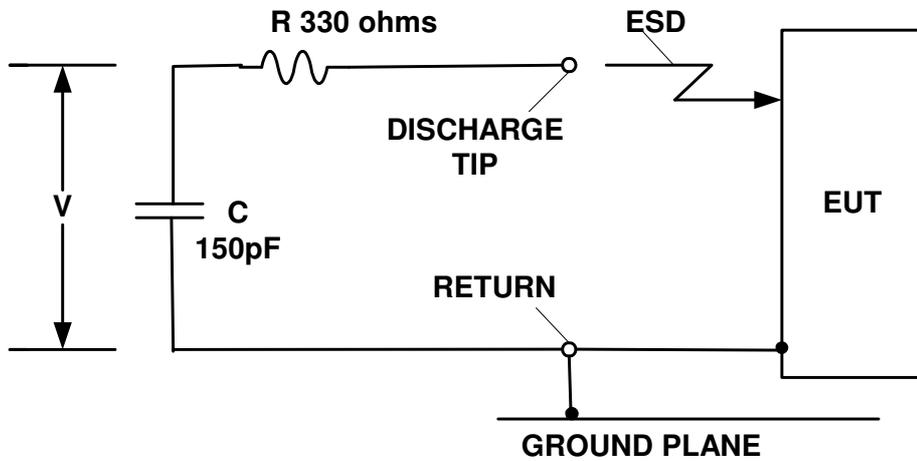


B. CONTRAST / RESPONSE TIME / VIEWING ANGLE

WESTAR CORPORATION FPM-510



C. ESD ON AIR DISCHARGE MODE



APPENDIX 3: PRECAUTIONS FOR USING THE OLED MODULE

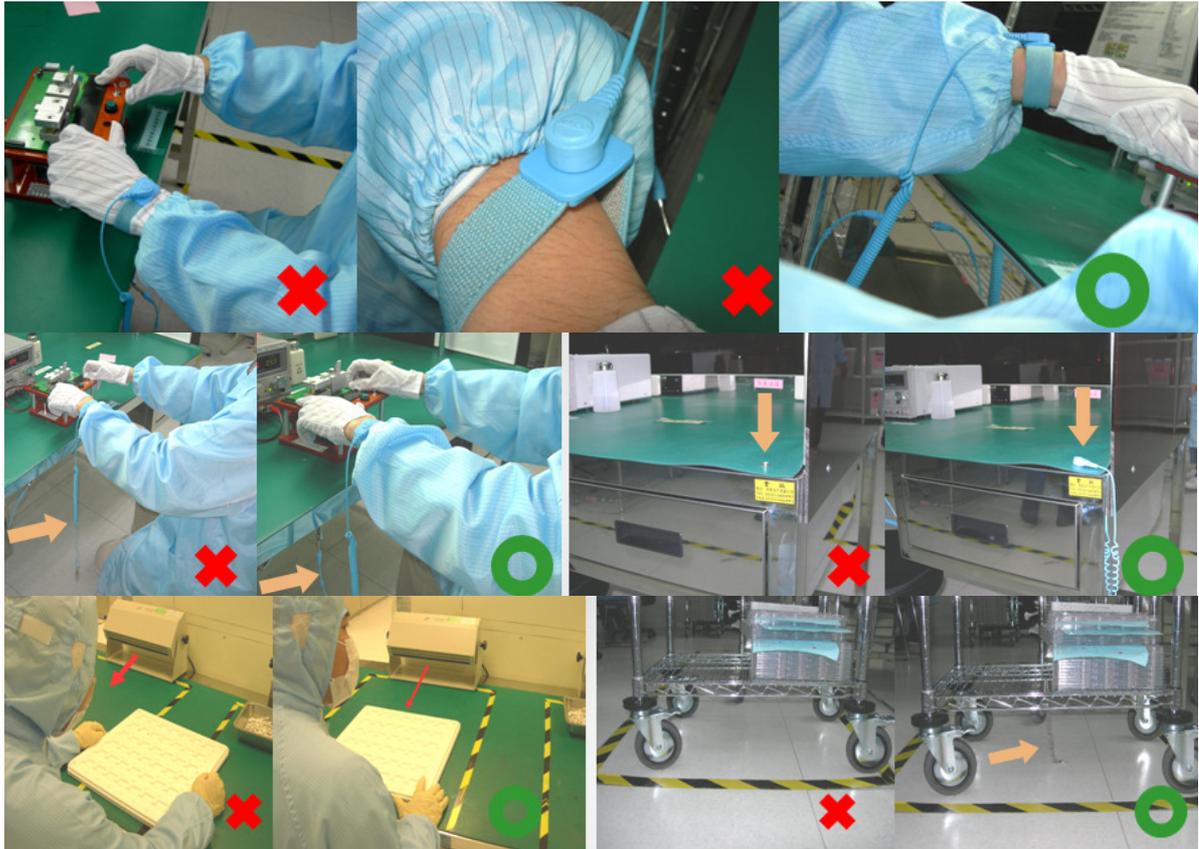
Precautions for Handling

1. When handling the module, wear powder-free anti static rubber finger cots/ anti-static clothing, anti-static gloves ,antistatic wrist strap and anti-static shoes

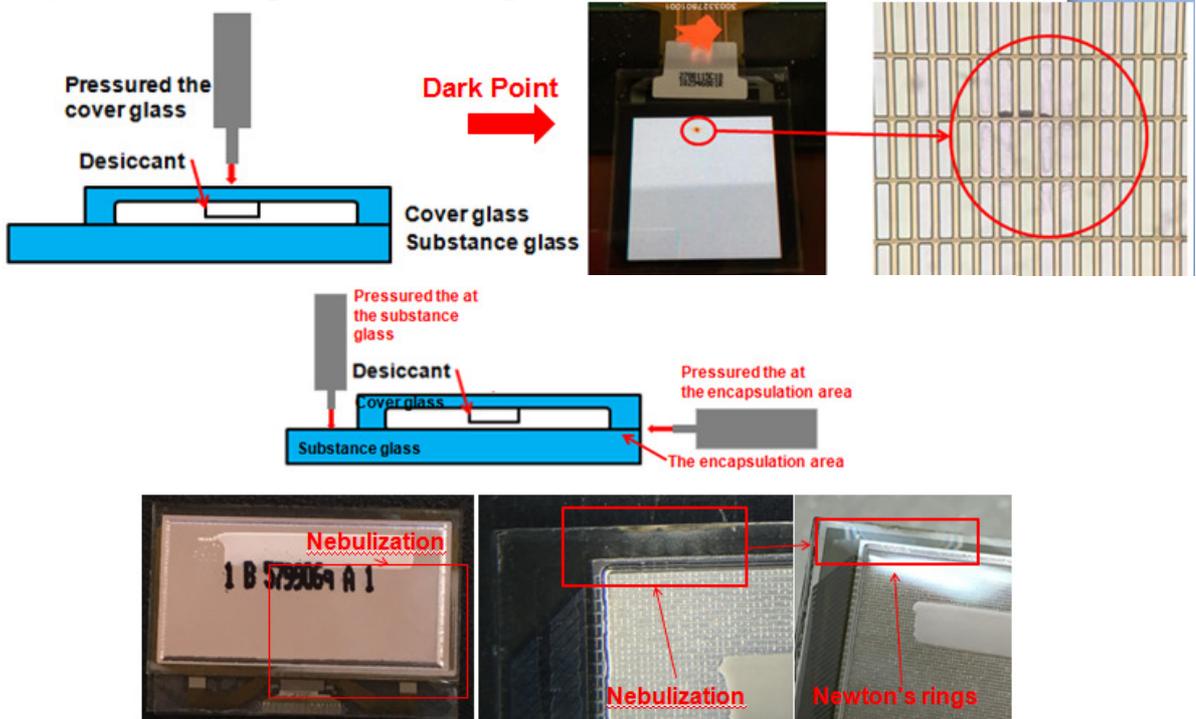
The environment should dispose the static elimination blower, anti-static pad, anti-static chair, and anti-static floor. The humidity maintains usually more than 40%



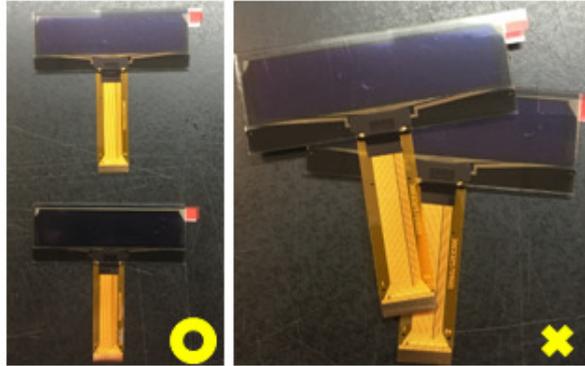
2. The OLED module is an electronic component and is subject to damage caused by Electro Static Discharge (ESD). And hence normal ESD precautions must be taken when handling it. Also, appropriate ESD protective environment must be administered and maintained in the production line. When handling and assembling the panel, wear an antistatic wrist strap with the alligator clip attached to the ground to prevent ESD damage on the panel. Antistatic wrist strap should touch human body directly instead of gloves. (See below photos).



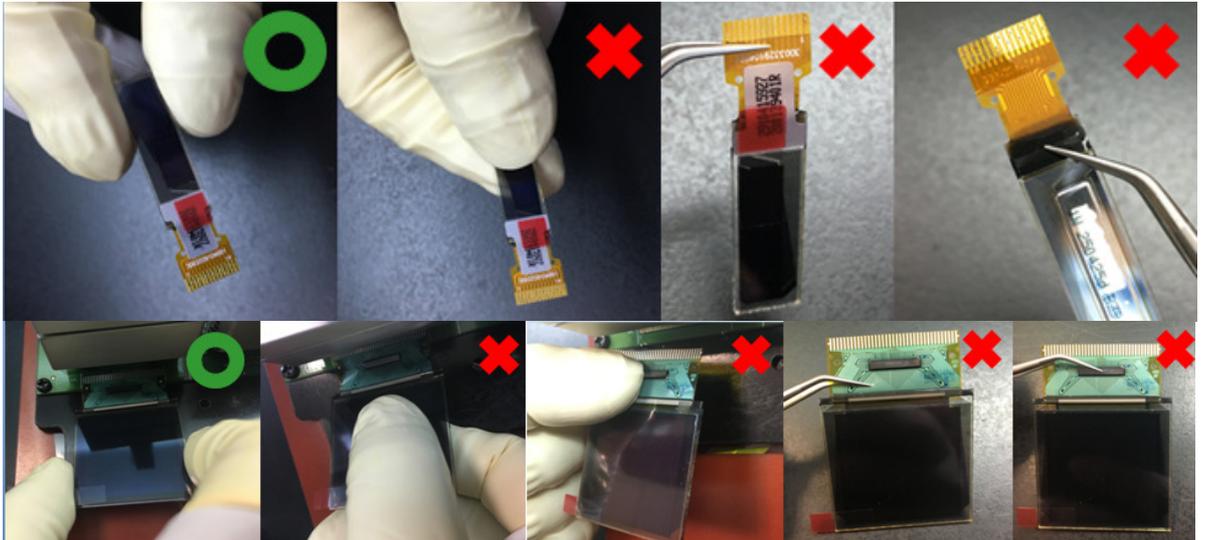
3. The OLED module is consisted of glass and film, and it should avoid pressure, strong impact, or being dropped from a high position.



- Take out the panel one by one from the holding trays for assembly, and never put the panel on top of another one to avoid the scratch.



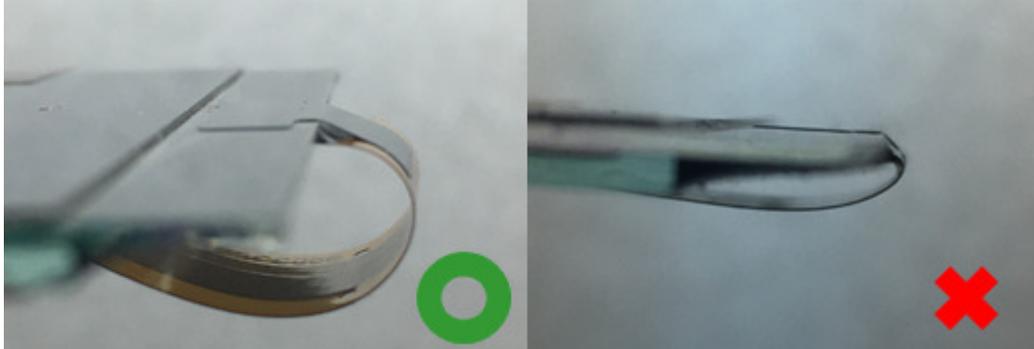
- Avoid jerk and excessive bend on TAB/FPC/COF, and be careful not to let foreign matter or bezel damage the film.
- When handling and assembling the module (panel + IC), grab the panel, not the TAB/FPC/COF.



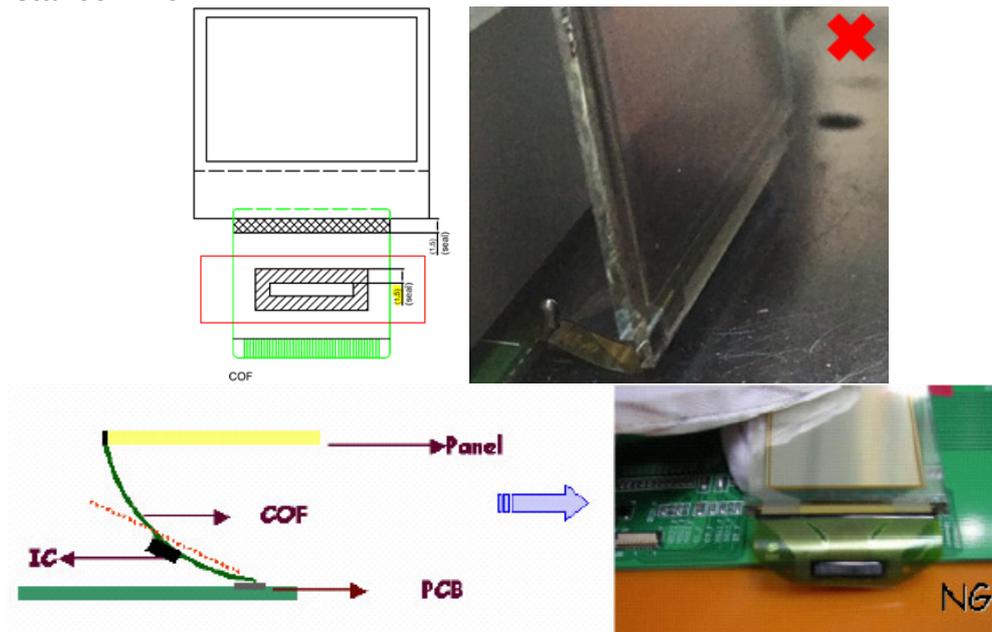
- Use the tweezers to open the clicks on the connector of PCB before the insertion of FPC/COF, and click them back in. Once the FPC/COF sits properly in the connector, use the tweezers to avoid the damages.



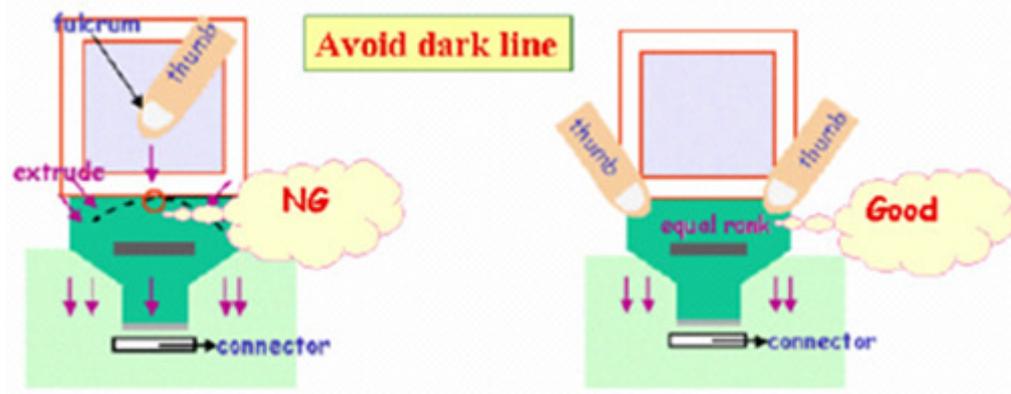
8. Please do not bend the film near the substrate glass. It could cause film peeling and TAB/FPC/COF damage. For TAB, It should bend the slit area as actual OLED it is. For FPC or COF, it is suggested to follow below pictures for instruction (distance between substrate glass and bending area >1.5mm; R>0.5mm).



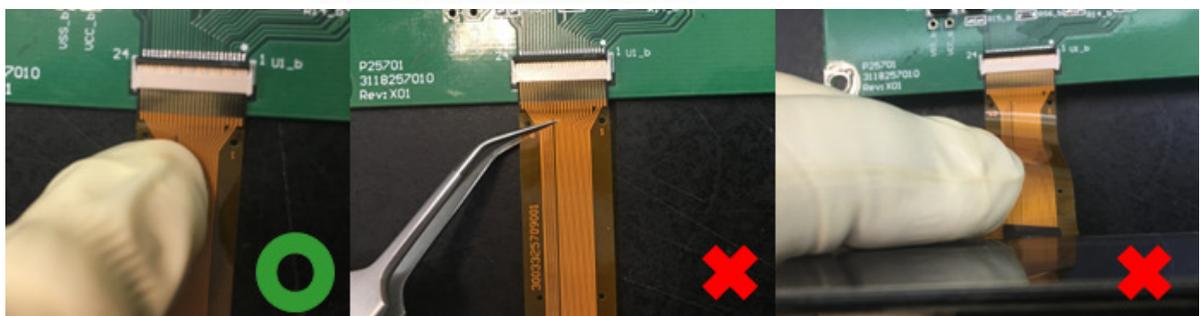
9. Avoid bending the film at IC bonding area. It could damage the IC ILB bonding. It should avoid bending the IC seal area. Please keep the bending distance >1.5mm.



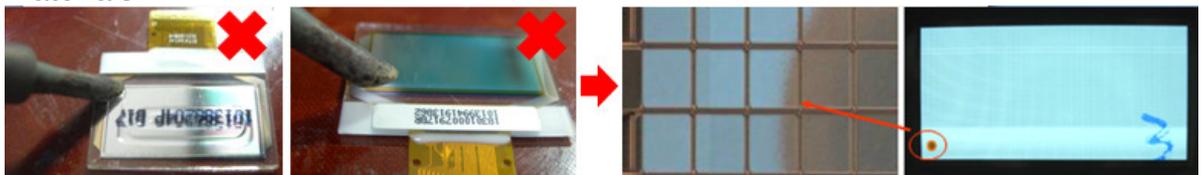
Use finger to insert COF /FPC into the connector when assembling the panel.
 Please refer to the photo.



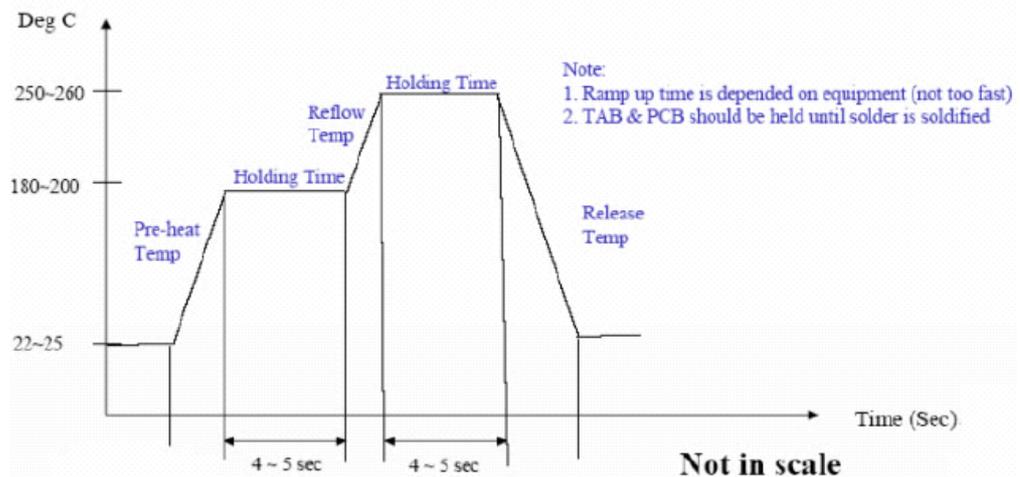
COF: Use both thumbs



10. Do not wipe the pin of film and polarizer with the dry or hard materials that will damage the surface. When cleaning the display surface, use the soft cloth with solvent, IPA or alcohol, to clean.
11. Protection film is applied to the surface of OLED panel to avoid the scratch. Please remove the protective film before assembling it. If the OLED panel has been stored for a long time, the residue adhesive material of the protective film may remain on the display surface after remove the protective film. Please use the soft cloth with solvent, IPA or alcohol, to clean.
12. When hand or hot-bar soldering TAB/FPC onto PCB, make sure the temperature and timing profiles to meet the requirements of soldering specification (the specification depends on the application or optimized by customer) to prevent the damage of IC pins by inappropriate soldering, and also avoid the high temperature to damage the Organic light-emitting materials.



13. Solder residues arise from soldering process have to be cleaned up thoroughly before the module assembly.
14. Use the voltage and current settings listed in the specification to do the function test after the module assembly.
15. Suggestion for soldering process:
 - i. TAB Lead- free soldering hot bar process
 1. Use pulse heated bonding tool equipment
 2. Material: Sn/Ag/Cu lead-free solder paste with typical 25um thickness on PCB pad. The TAB pin size and shape may be different, please base on the production line to adjust the thickness of PCB pad and temperature.S
 3. Bonding Force:--4kg per centimeter square as the starting point.
 4. Suggested bonding tool temperature & time profile is as below for reference. Since there are differences in TAB soldering pins, soldering technicians' skills, mechanism...etc., the soldering conditions must be adequately tuned.



- ii. TAB Lead- free soldering wire process

In case of manual soldering (Lead- free solder wire)

 1. Solder wire contact iron directly: $280 \pm 5^\circ\text{C}$ at 3-5secs
 2. Solder wire contact TAB lead directly (near iron but not contact): $380 \pm 5^\circ\text{C}$, 3-5secs
 3. Since there are differences in TAB soldering pins, soldering technicians' skills, mechanism...etc., the soldering conditions must be adequately tuned.
- iii. High temperature will result in rapid heat conduction to IC and might cause damage to IC, so please keep the temperature below 380°C . Also, avoid damaging the polyimide and solder resist which might take place at high temperatures. Refold cycles base on the de-soldering status, if the plating of pin was damaged, it can not be used again.

Precautions for Electrical

1. Design using the settings in the specification

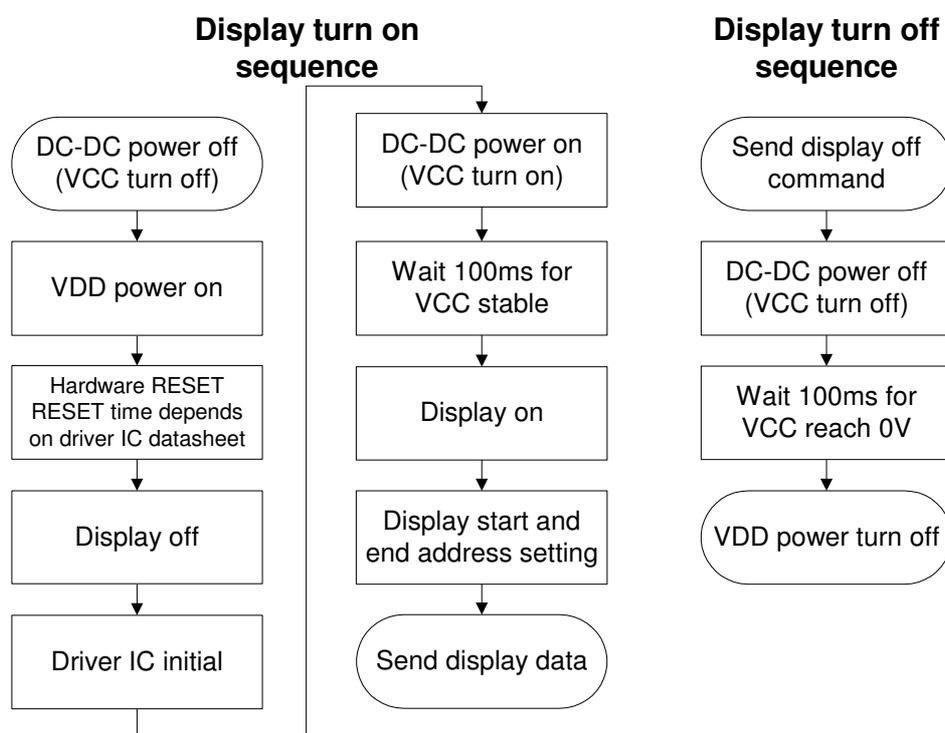
It is very important to design and operate the panel using the settings listed in the specification. It includes voltage, current, frame rate and duty cycle... etc. Operation the OLED outside the range of the specification should be entirely avoided to ensure proper operation of the OLED.

2. Maximum Ratings

To ensure the proper operation of the panel, never design the panel with parameters running over the maximum ratings listed in the specification. Also the logic voltages such as VIL and VIH have to be within the specified range in the specification to prevent any improper operation of the panel.

3. Power on/off procedure

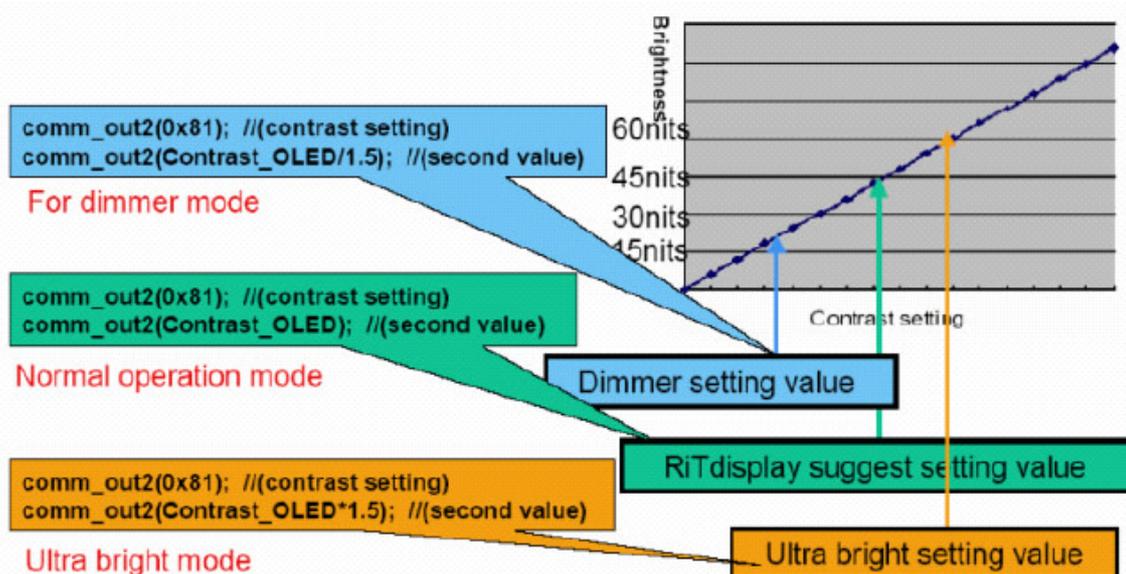
To avoid any inadvertent effects resulting from inappropriate power on/off operations, please follow the directions of power on/off procedure on page 6. Any operation that does not comply with the procedure could cause permanent damage of the IC and should be avoided. When the logic power is not on, do not activate any input signal. Abrupt shutdown of power to the module, while the OLED panel is on, would cause OLED panel malfunction.



4. Power savings

To save power consumption of the OLED, please use partial display or sleep mode when the panel is not fully activated. Also, if possible, make the black background to save power.

The OLED is a self-luminous device and a particular pixel cluster or image can be lit on via software control. So power savings can be achieved by partial display or dimming down the luminance. Depending on the application, the user can choose among Ultra Bright Mode, Normal Operation Mode, and Sleeping Mode. The power consumption is almost in directly proportion to the brightness of the panel, and also in directly proportion to the number of pixels lit on the panel. The customer can save the power by the use of black background and sleeping mode. One benefit from using these design schemes is the extension of the OLED lifetime.



5. Adjusting the luminance of the panel

Although there are a couple of ways to adjust the luminance of the panel, it is strongly recommended that the customer change the contrast setting to adjust the luminance of the panel. Adjusting voltages to achieve desired luminance is not allowed. Be aware that the adjustment of luminance would accompany the change of lifetime of the panel and its power consumption as well.

6. Residual Image (Image Sticking)

The OLED is a self-emissive device. As with other self-emissive device or displays consisting of self-emissive pixels, when a static image frozen for a long period of time is changed to another one with all-pixels-on background, residual image or image sticking is noticed by the human eye. Image sticking is due to the luminance difference or contrast between the pixels that were previously turned on and the pixels that are newly turned on. Image sticking depends on the luminance decay curve of the display. The slower the decay, the less prominent the image sticking is. It is strongly recommended that the user employ the following four strategies to minimize image sticking.

1. Employ image scrolling or animation to even out the lit-on time of each and every pixel on the display, also could use sleeping mode for reduced the residual image and extend the power capacity.
2. Minimize the use of all-pixels-on or full white background in their application because when the panel is turned on full white, the image sticking from previously shown patterns is the most revealing. Black background is the best for power savings, greatest visibility, eye appealing, and dazzling displays.
3. Avoid displaying the characters or menu with high brightness level in a fix position for a long time or repeatedly. If necessary, using the auto fadeout technology.
4. If a static logo is used in the reliability test, change the pattern into its inverse (i.e., turn off the while pixels and turn on the previously unlit pixels) and freeze the inverse pattern as long as the original logo is used, so every pixel on the panel can be lit on for about the same time to minimize image sticking, caused by the differential turn-on time between the original and its reverse patterns.



Scrolling example

Frame1

Frame2

Frame3

Frame4

Frame5

Example: setup and start

```

comm_out2(0x26); // scrolling setup
comm_out2(0x08); // scrolling numbers/step
comm_out2(0x00); // start page
comm_out2(0x00); // scrolling step/frame
comm_out2(0x08); // end page
comm_out2(0x2F); // start
    
```

Example: stop

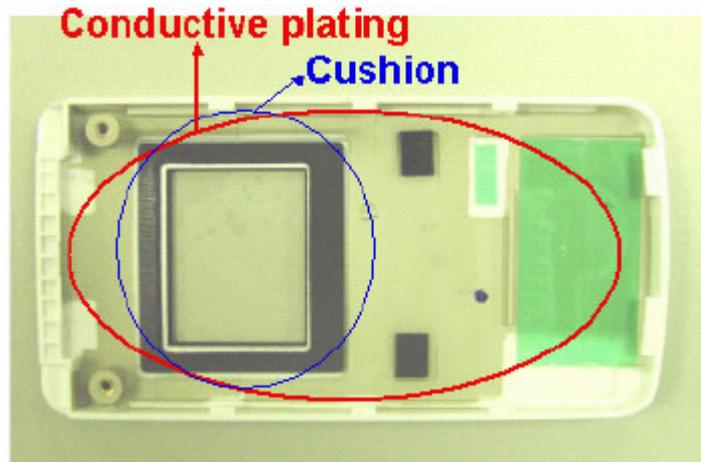
```

comm_out2(0x2E); //stop
    
```

Precautions for Mechanical

1. Cushion or Buffer tape on the cover glass

It is strongly recommended to have a cushion or buffer tape to apply on the panel backside and front side when assembling OLED panel into module to protect it from damage due to excessive extraneous forces.



It is recommended that a plating conductive layer be used in the housing for EMI/EMC protection. And, the enough space should be reserved for the IC placement if the IC thickness is thicker than the TAB film when customer design the PCB.

2. Avoid excessive bending of film when handling or designing the panel into the product

The bending of TAB/COF/FPC has to follow the precautions indicated in the specification, extra bending or excessive extraneous forces should be avoided to minimize the chances of film damage. If bending the film is necessary, please bend the designated bending area only. Please refer to items 8 and 9 of Precautions for Handling for more information.

Precautions for Storage and Reliability Test

1. Storage

Store the packed cartons or packages at $25^{\circ}\text{C}\pm 5^{\circ}\text{C}$, $55\%\pm 10\%\text{RH}$. Do not store the OLED module under direct sunlight or UV light. For best panel performance, unpack the cartons and start the production of the panels within six months after the reception of them.

2. Reliability Test

RiTdisplay only guarantees the reliability of the OLEDs under the test conditions and durations listed in the specification.